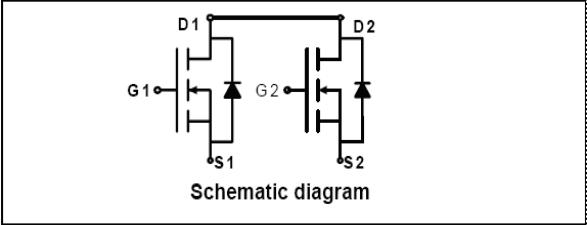
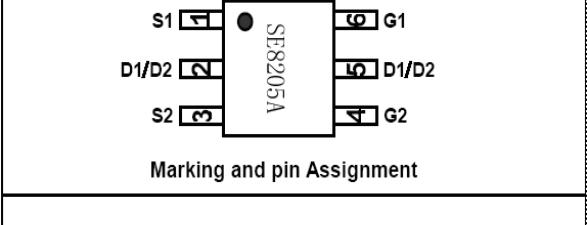


SE8205A
N-Channel Enhancement Mode Field Effect Transistor

Revision:B

<p>Features</p> <ul style="list-style-type: none"> ● $V_{DS} = 20V, I_D = 6A$ ● $R_{DS(ON)} < 34.5m\Omega @ V_{GS} = 2.5V$ ● $R_{DS(ON)} < 24.5m\Omega @ V_{GS} = 4.5V$ ● High Power and current handing capability ● Lead free product is acquired ● Surface Mount Package 	<p>External Dimensions: (Unit:mm)</p>  <p>Schematic diagram</p>  <p>Marking and pin Assignment</p>  <p>SOT23-6 top view</p>
<p>Applications</p> <ul style="list-style-type: none"> ● Battery protection ● Load switch ● Power management 	
<p>Construction</p> <ul style="list-style-type: none"> ● Silicon epitaxial planer 	

Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 10	V
Drain Current-Continuous@ Current-Pulsed (Note 1)	I_D	6	A
Maximum Power Dissipation	P_D	25	A
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	°C

THERMAL CHARACTERISTICS

Thermal Resistance,Junction-to-Ambient (Note 2)	$R_{\theta JA}$	83	°C/W
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Electrical characteristics (Ta=25°C)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20V, V_{GS}=0V$			0.8	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 10V, V_{DS}=0V$			± 80	nA

SE8205A

ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.45	0.65	1.2	V	
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 4.5A$		21	24.5	$m\Omega$	
		$V_{GS} = 2.5V, I_D = 3.5A$		30	34.5	$m\Omega$	
Forward Transconductance	g_{FS}	$V_{DS} = 5V, I_D = 4.5A$	3			S	
DYNAMIC CHARACTERISTICS (Note 4)							
Input Capacitance	C_{iss}	$V_{DS} = 8V, V_{GS} = 0V, F = 1.0MHz$		600		PF	
Output Capacitance	C_{oss}			330		PF	
Reverse Transfer Capacitance	C_{rss}			140		PF	
SWITCHING CHARACTERISTICS (Note 4)							
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 10V, I_D = 1A$ $V_{GS} = 4.5V, R_{GEN} = 6\Omega$		10	20	nS	
Turn-on Rise Time	t_r			11	25	nS	
Turn-Off Delay Time	$t_{d(off)}$			35	70	nS	
Turn-Off Fall Time	t_f			30	60	nS	
Total Gate Charge	Q_g	$V_{DS} = 10V, I_D = 6A, V = 4.5V$		10	15	nC	
Gate-Source Charge	Q_{gs}			2.3		nC	
Gate-Drain Charge	Q_{gd}			3		nC	
DRAIN-SOURCE DIODE CHARACTERISTICS							
Diode Forward Voltage (Note 3)	V_{SD}	$V = 0V, I = 1.7A$			1.2	V	
Diode Forward Current (Note 2)	I_s			1.7		A	

NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production testing.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

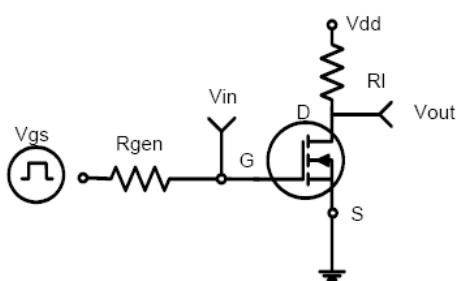


Figure 1:Switching Test Circuit

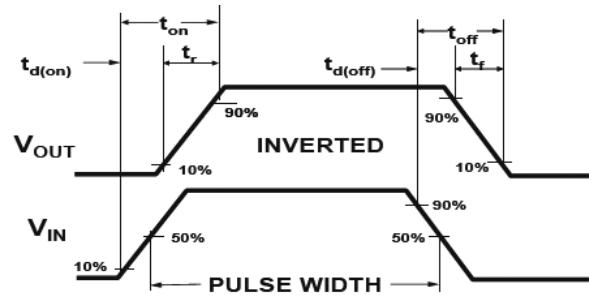


Figure 2:Switching Waveforms

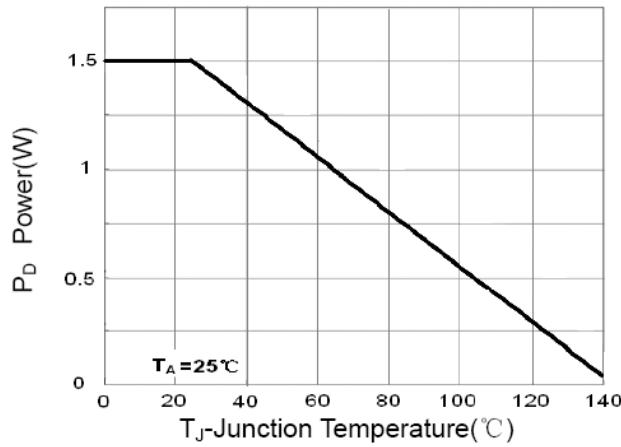


Figure 3 Power Dissipation

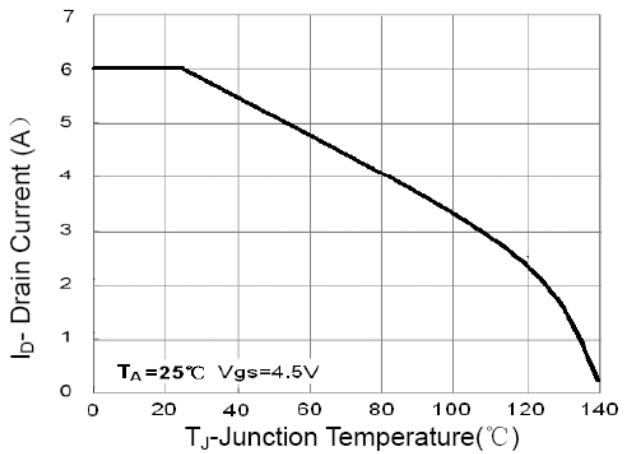


Figure 4 Drain Current

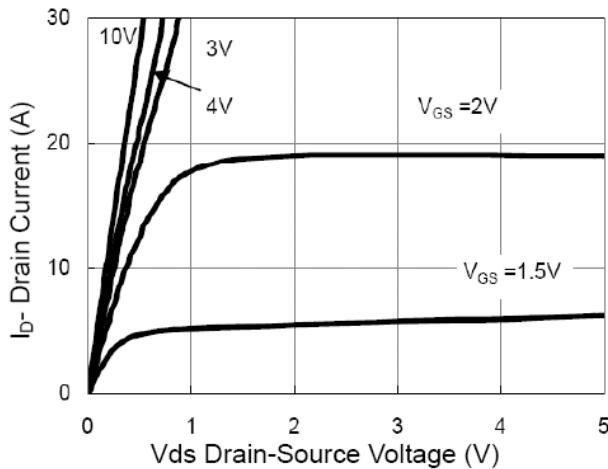


Figure 5 Output CHARACTERISTICS

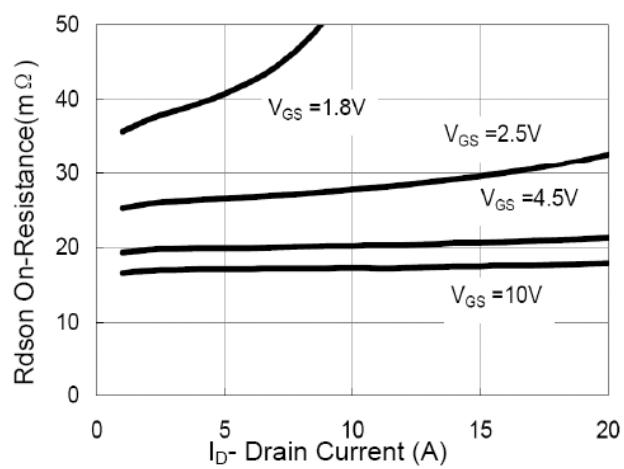


Figure 6 Drain-Source On-Resistance

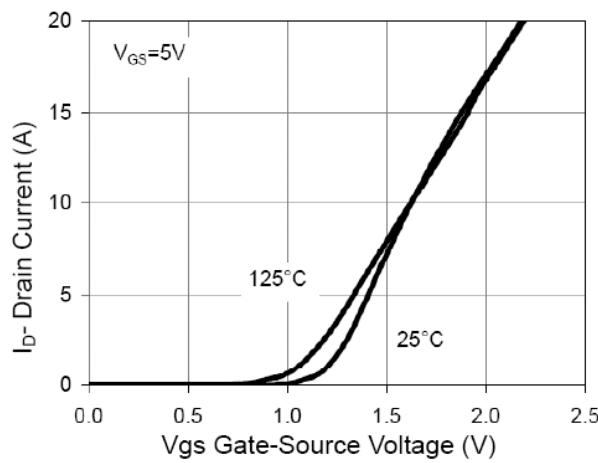


Figure 7 Transfer Characteristics

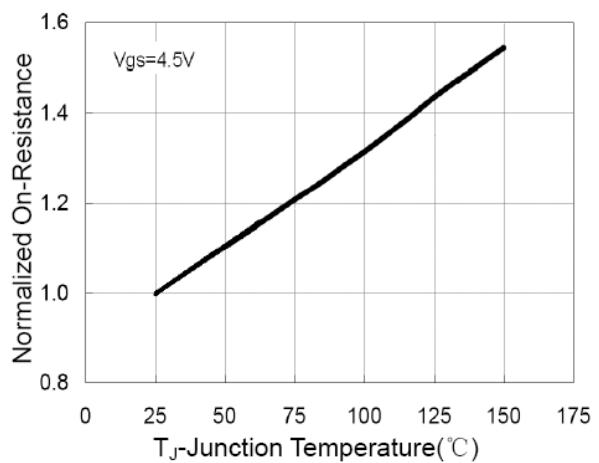


Figure 8 Drain-Source On-Resistance

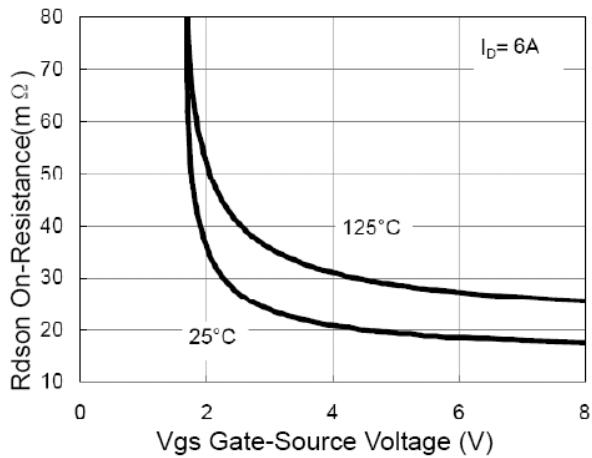


Figure 9 $R_{DS(on)}$ vs V_{GS}

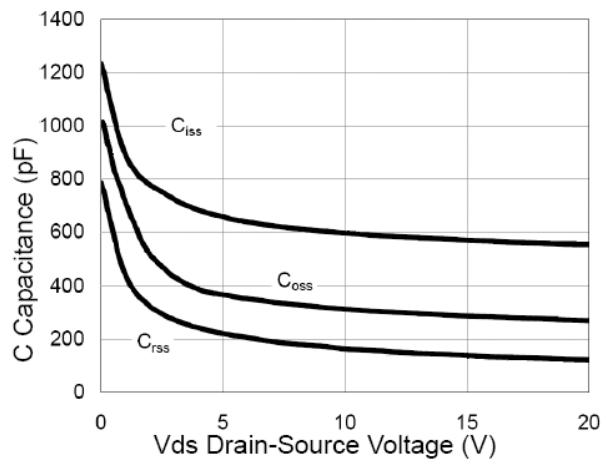


Figure 10 Capacitance vs V_{DS}

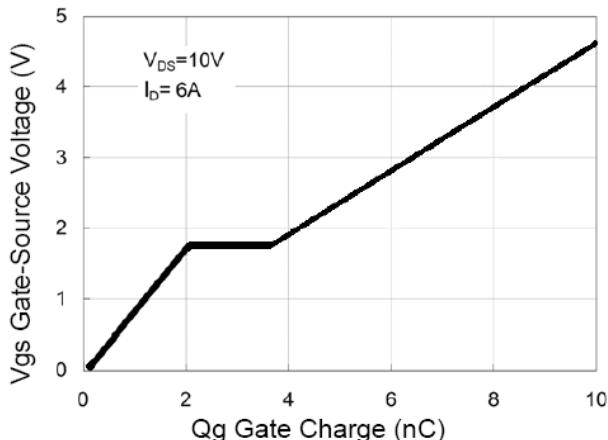


Figure 11 Gate Charge

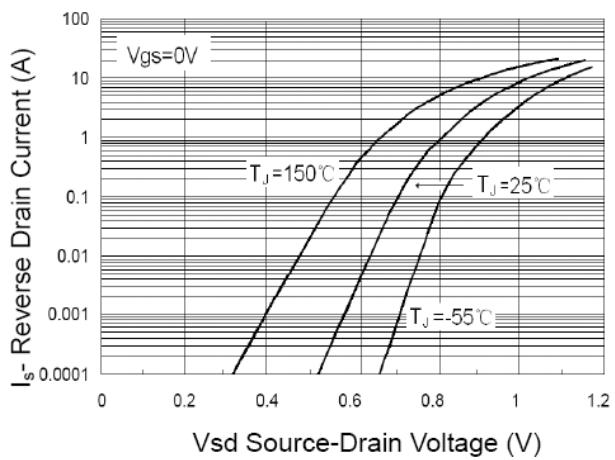


Figure 12 Source-Drain Diode Forward

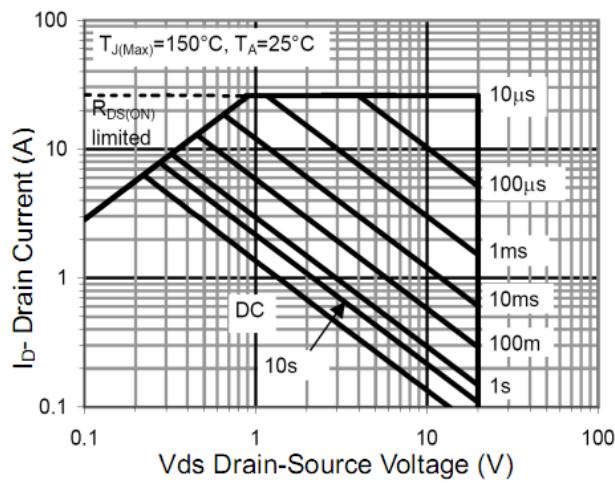


Figure 13 Safe Operation Area

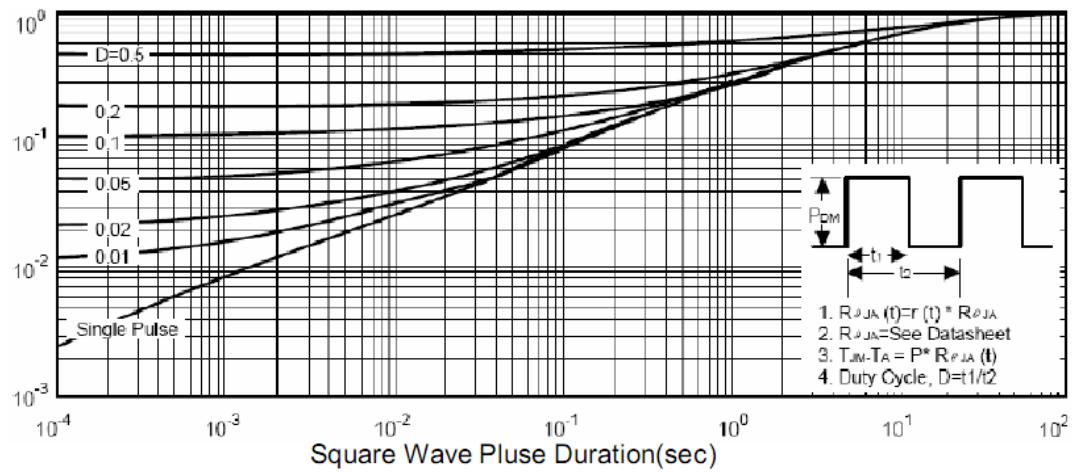
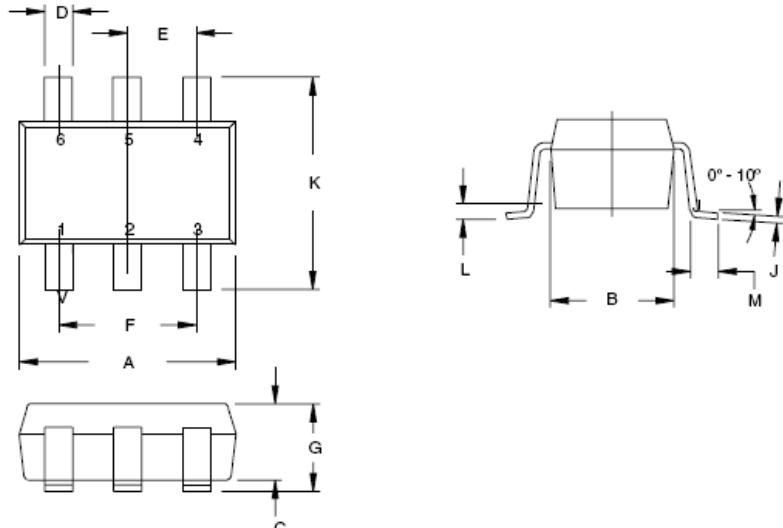


Figure 14 Normalized Maximum Transient Thermal Impedance

PACKAGE OUTLINE



PACKAGE DIMENSIONS				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.80	3.05	0.110	0.120
B	1.50	1.75	0.059	0.070
C	0.90	1.30	0.036	0.051
D	0.35	0.50	0.014	0.020
E	0.85	1.05	0.033	0.040
F	1.70	2.10	0.067	0.083
G	0.90	1.45	0.036	0.057
J	0.090	0.20	0.0035	0.008
L	0.20TYP	0.20TYP	0.007TYP	0.007TYP
M	0.35	0.55	0.014	0.022

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